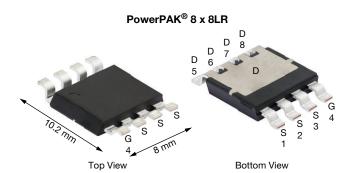


Vishay Siliconix

# Automotive N-Channel 100 V (D-S) 175 °C MOSFET



PRODUCT SUMMARY				
V <sub>DS</sub> (V)	100			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$	0.00253			
I <sub>D</sub> (A)	296			
Configuration	Single			

#### **FEATURES**

- TrenchFET® Gen IV power MOSFET
- AEC-Q101 qualified
- 100 % R<sub>q</sub> and UIS tested
- Thin 1.9 mm height
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>



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N-Channel MOSFET S	

ORDERING INFORMATION	
Package	PowerPAK 8 x 8LR
Lead (Pb)-free and halogen-free	SQJQ112ER (for detailed order number please see <a href="https://www.vishay.com/doc?79776">www.vishay.com/doc?79776</a> )

<b>ABSOLUTE MAXIMUM RATING</b>	<b>3S</b> ( $T_C = 25$ °C, unles	s otherwise noted	d)		
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage	V <sub>DS</sub>	100	V		
Gate-source voltage	$V_{GS}$	± 20			
Continuous drain current	T <sub>C</sub> = 25 °C	1	296		
	T <sub>C</sub> = 125 °C	I <sub>D</sub>	171		
Continuous source current (diode conduction	I <sub>S</sub>	545	А		
Pulsed drain current <sup>a</sup>		I <sub>DM</sub>		655	
Single pulse avalanche current	L = 0.1 mH	I <sub>AS</sub>	69		
Single pulse avalanche energy	L = 0.1 IIII	E <sub>AS</sub>	242	mJ	
Maximum power dissipation	T <sub>C</sub> = 25 °C	Б	600	W	
	T <sub>C</sub> = 125 °C	$P_{D}$	200		
Operating junction and storage temperature range		T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C	
Soldering recommendations (peak temperature) c		-	260		

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	LIMIT	UNIT	
Junction-to-ambient	PCB mount b	$R_{thJA}$	40	9C AM	
Junction-to-case (drain)		R <sub>thJC</sub>	0.25	°C/W	

#### Notes

- a. Pulse test; pulse width  $\leq 300~\mu\text{s},$  duty cycle  $\leq 2~\%$
- b. When mounted on 1" square PCB (FR4 material)
- c. See solder profile (www.vishay.com/doc?73257)



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PARAMETER	SYMBOL	TES	T CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static								
Drain-source breakdown voltage	V <sub>DS</sub>	V <sub>GS</sub> = 0, I <sub>D</sub> = 250 μA		100	-	-	V	
Gate-source threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =	= V <sub>GS</sub> , I <sub>D</sub> = 250 μA	2	3	3.5	V	
Gate-source leakage	I <sub>GSS</sub>	V <sub>DS</sub> =	0 V, V <sub>GS</sub> = ± 20 V	-	-	± 100	nA	
Zero gate voltage drain current		$V_{GS} = 0 V$	V <sub>DS</sub> = 100 V	-	-	1		
	I <sub>DSS</sub>	$V_{GS} = 0 V$	V <sub>DS</sub> = 100 V, T <sub>J</sub> = 125 °C	-	-	50	μΑ	
		$V_{GS} = 0 V$	V <sub>DS</sub> = 100 V, T <sub>J</sub> = 175 °C	1	-	500		
On-state drain current <sup>a</sup>	I <sub>D(on)</sub>	$V_{GS} = 10 \text{ V}$	$V_{DS} \ge 5 V$	50	-	-	Α	
		$V_{GS} = 10 \text{ V}$	I <sub>D</sub> = 20 A	1	0.0021	0.00253		
Drain-source on-state resistance a	R <sub>DS(on)</sub>	$V_{GS} = 10 \text{ V}$	I <sub>D</sub> = 20 A, T <sub>J</sub> = 125 °C	1	-	0.0054	Ω	
		$V_{GS} = 10 \text{ V}$	I <sub>D</sub> = 20 A, T <sub>J</sub> = 175 °C	1	-	0.0068		
Forward transconductance b	9 <sub>fs</sub>	$V_{DS}$	= 15 V, I <sub>D</sub> = 15 A	1	45	-	S	
Dynamic <sup>b</sup>								
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0 V	/ V <sub>DS</sub> = 25 V, f = 1 MHz	-	11388	15 945	pF	
Output capacitance	Coss			-	1326	1857		
Reverse transfer capacitance	C <sub>rss</sub>			-	80	112		
Total gate charge <sup>c</sup>	$Q_g$			1	181	272	nC	
Gate-source charge <sup>c</sup>	$Q_{gs}$	$V_{gs}$ $V_{GS} = 10 \text{ V}$ $V_{DS} = 50 \text{ V}, I_D = 20 \text{ A}$	$V_{DS} = 50 \text{ V}, I_D = 20 \text{ A}$	1	48	-		
Gate-drain charge <sup>c</sup>	$Q_{gd}$				37	-	<u>l</u>	
Gate resistance	$R_g$	f = 1 MHz		0.7	1.5	2.3	Ω	
Turn-on delay time <sup>c</sup>	t <sub>d(on)</sub>			1	21	30		
Rise time <sup>c</sup>	t <sub>r</sub>		$= 50 \text{ V}, \text{ R}_{\text{L}} = 2.5 \Omega,$	1	16	24	]	
Turn-off delay time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong 20 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		ı	67	95	ns	
Fall time <sup>c</sup>	t <sub>f</sub>			1	16	24		
Source-Drain Diode Ratings and Charact	teristics <sup>b</sup>							
Pulsed current <sup>a</sup>	I <sub>SM</sub>			-	-	655	Α	
Forward voltage	$V_{SD}$	I <sub>F</sub> = 40 A, V <sub>GS</sub> = 0 V		-	0.7	1.2	V	
Body diode reverse recovery time	t <sub>rr</sub>	I <sub>F</sub> = 15 A, di/dt = 100 A/μs		-	70	140	ns	
Body diode reverse recovery charge	Q <sub>rr</sub>			-	172	344	nC	
Reverse recovery fall time	t <sub>a</sub>			-	44	-		
Reverse recovery rise time	t <sub>b</sub>			-	26	-	ns	
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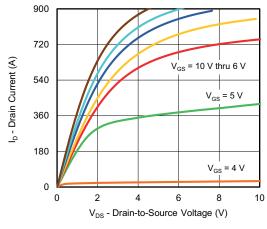
#### Notes

- a. Pulse test; pulse width  $\leq 300~\mu s,~duty~cycle \leq 2~\%$
- b. Guaranteed by design, not subject to production testing
- c. Independent of operating temperature

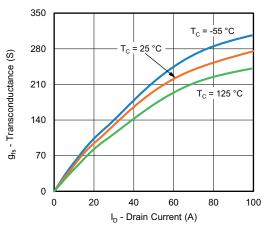
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



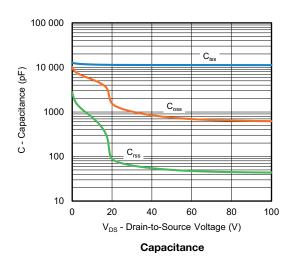
## **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)

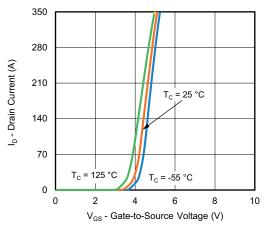


#### **Output Characteristics**

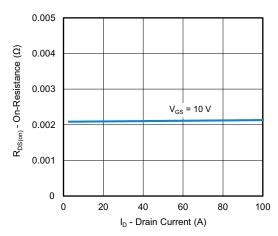


Transconductance

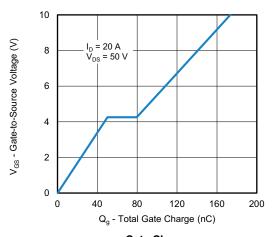




**Transfer Characteristics** 

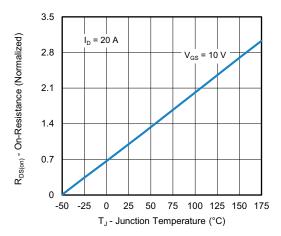


**On-Resistance vs. Drain Current** 

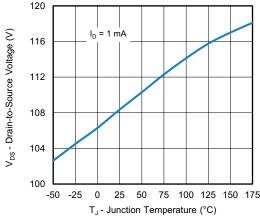




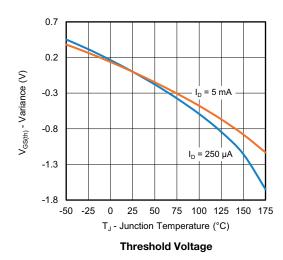
### **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)

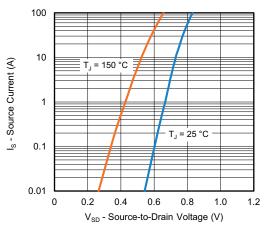


On-Resistance vs. Junction Temperature

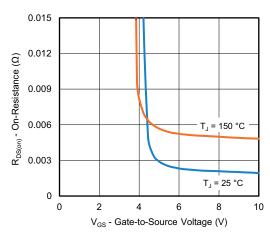


Drain Source Breakdown vs. Junction Temperature

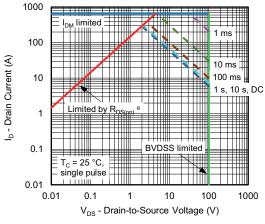




**Source Drain Diode Forward Voltage** 



On-Resistance vs. Gate-to-Source Voltage



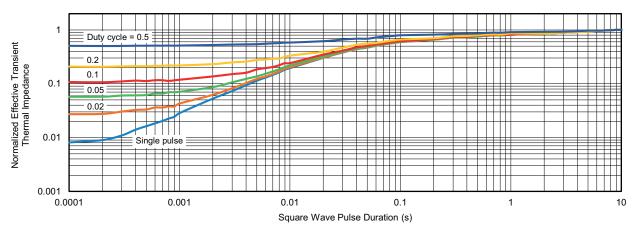
Safe Operating Area

#### Note

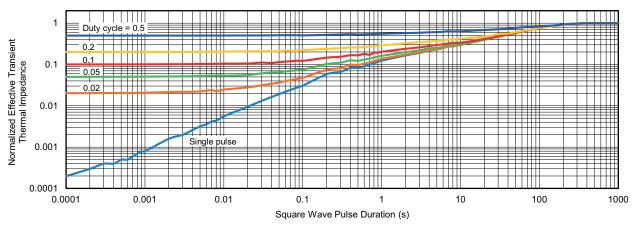
a.  $V_{GS} > minimum V_{GS}$  at which  $R_{DS(on)}$  is specified



### **THERMAL RATINGS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case



Normalized Thermal Transient Impedance, Junction-to-Ambient

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